

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

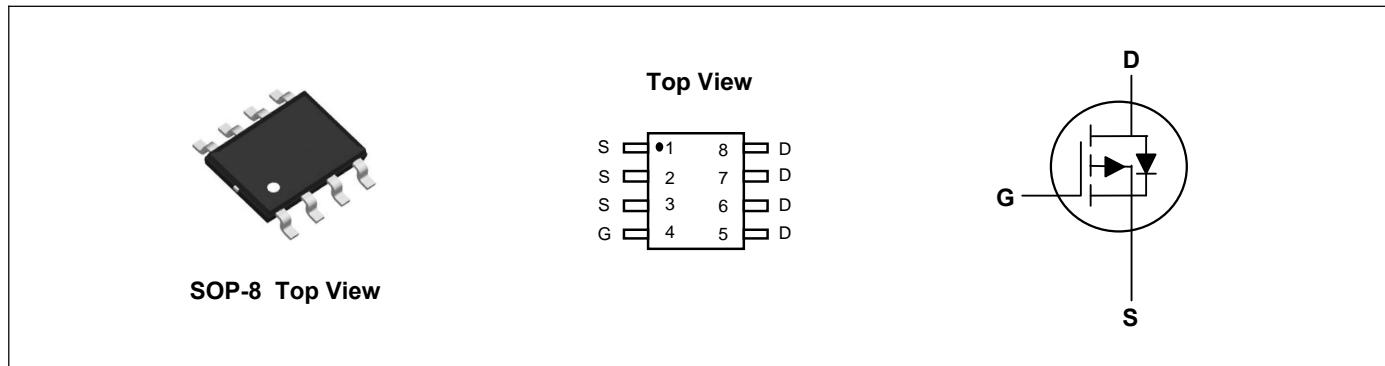
Product Summary



| | | |
|-----------------------------------|-----|----|
| V_{DS} | -40 | V |
| I_D | -11 | A |
| $R_{DS(ON)}$ (at $V_{GS}=-10V$) | 16 | mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) | 22 | mΩ |

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED Back Light



Absolute Maximum Ratings($T_A=25^\circ C$, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|--|------------------------|------------|-------|
| Drain-Source Voltage | V_{DS} | -40 | V |
| Gate-Source Voltage | V_{GS} | ± 25 | V |
| Continuous Drain Current ¹ | $I_D @ T_A=25^\circ C$ | -11 | A |
| Continuous Drain Current ¹ | $I_D @ T_A=70^\circ C$ | -9 | A |
| Pulsed Drain Current ² | I_{DM} | -44 | A |
| Single Pulse Avalanche Energy ³ | EAS | 54 | mJ |
| Avalanche Current | I_{AS} | -33 | A |
| Total Power Dissipation ⁴ | $P_D @ T_A=25^\circ C$ | 3.1 | W |
| Total Power Dissipation ⁴ | $P_D @ T_A=70^\circ C$ | 2.0 | W |
| Storage Temperature Range | T_{STG} | -55 to 150 | °C |
| Operating Junction Temperature Range | T_J | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Unit |
|---|-----------------|-----|-----|------|
| Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$) | $R_{\theta JA}$ | --- | 40 | °C/W |
| Thermal Resistance Junction-Ambient ¹ (Steady State) | | --- | 75 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | --- | 24 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|-----------------------------------|---|------|------|-----------|------------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$ | -40 | --- | --- | V |
| Static Drain-Source On-Resistance ² | $\text{R}_{\text{DS}(\text{ON})}$ | $\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-1\text{A}$ | --- | 13 | 16 | $\text{m}\Omega$ |
| | | $\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-7\text{A}$ | --- | 18 | 22 | $\text{m}\Omega$ |
| Gate Threshold Voltage | $\text{V}_{\text{GS}(\text{th})}$ | $\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D = -250\mu\text{A}$ | -1.4 | -1.9 | -2.4 | V |
| Drain-Source Leakage Current | I_{DSS} | $\text{V}_{\text{DS}}=-32\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | -1 | uA |
| | | $\text{V}_{\text{DS}}=-32\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=85^\circ\text{C}$ | --- | --- | -30 | uA |
| Gate-Source Leakage Current | I_{GSS} | $\text{V}_{\text{GS}}=\pm 25\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| Gate Resistance | R_g | $\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 2.3 | --- | Ω |
| Total Gate Charge | Q_g | $\text{V}_{\text{DS}}=-20\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-1\text{A}$ | --- | 32 | --- | nC |
| Gate-Source Charge | Q_{gs} | | --- | 5.2 | --- | |
| Gate-Drain Charge | Q_{gd} | | --- | 8 | --- | |
| Turn-On Delay Time | $\text{T}_{\text{d}(\text{on})}$ | $\text{V}_{\text{DD}}=-20\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{R}_G=6\Omega$, $\text{I}_D=-1\text{A}$, $\text{R}_L=20\Omega$ | --- | 14 | --- | ns |
| Rise Time | T_r | | --- | 12 | --- | |
| Turn-Off Delay Time | $\text{T}_{\text{d}(\text{off})}$ | | --- | 41 | --- | |
| Fall Time | T_f | | --- | 22 | --- | |
| Input Capacitance | C_{iss} | $\text{V}_{\text{DS}}=-20\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1500 | --- | pF |
| Output Capacitance | C_{oss} | | --- | 235 | --- | |
| Reverse Transfer Capacitance | C_{rss} | | --- | 180 | --- | |

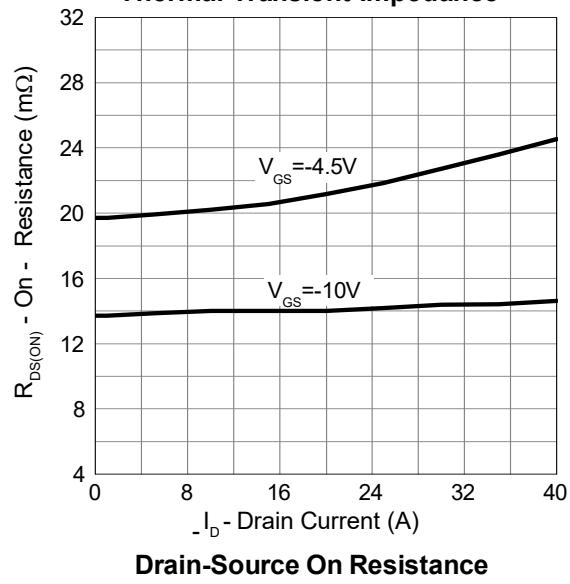
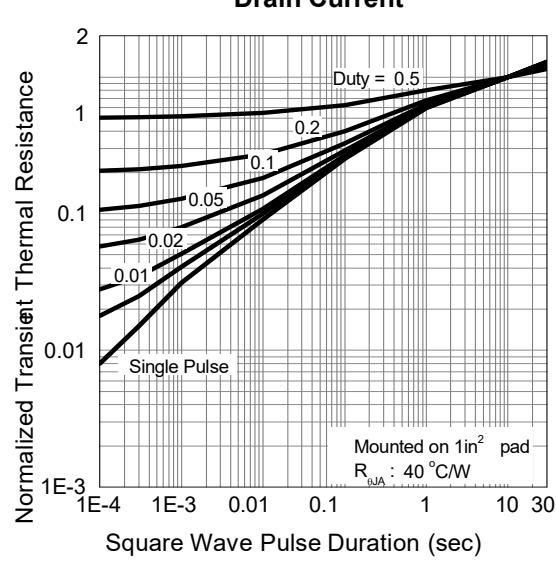
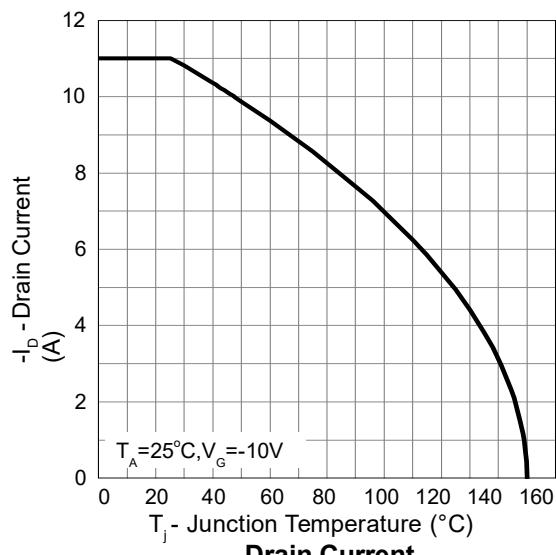
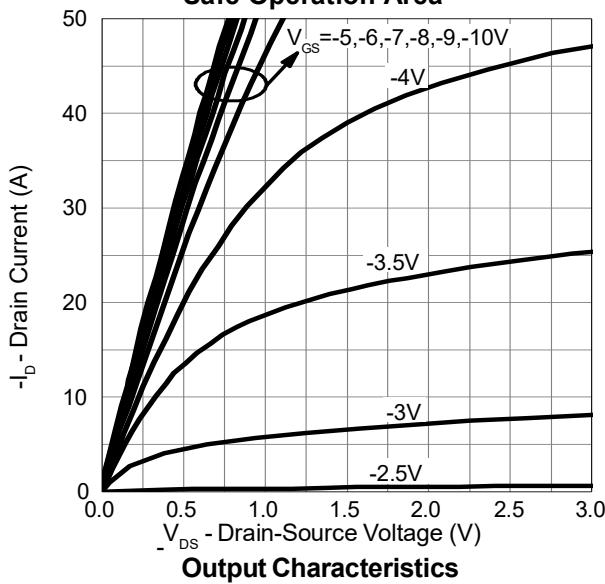
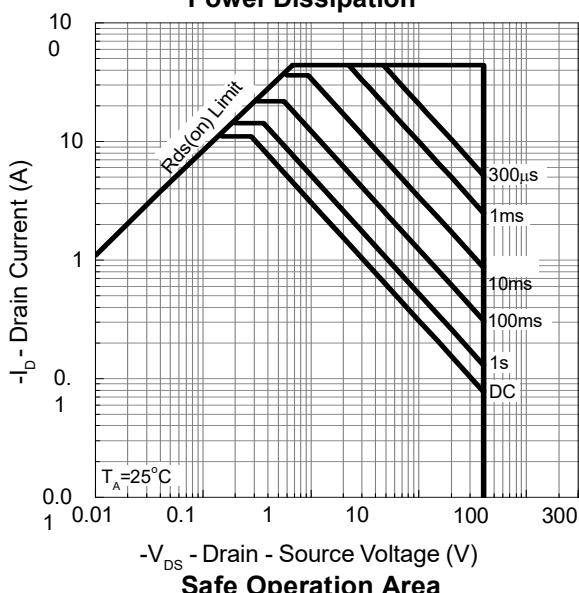
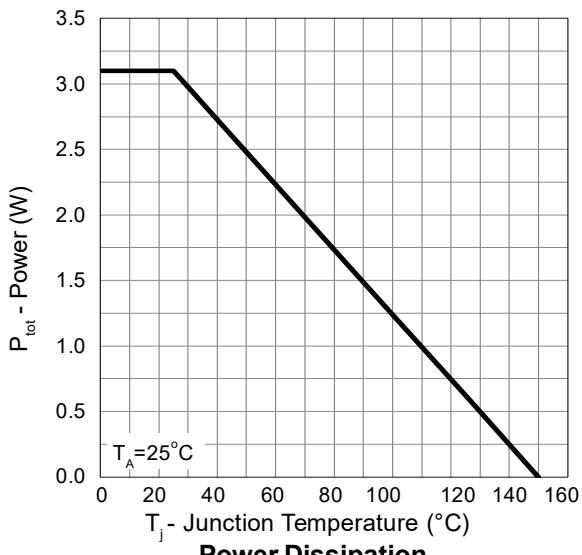
Drain-Source Diode Characteristics

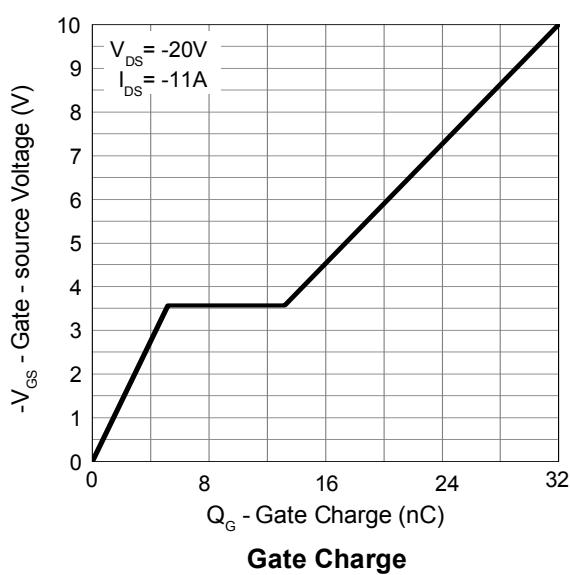
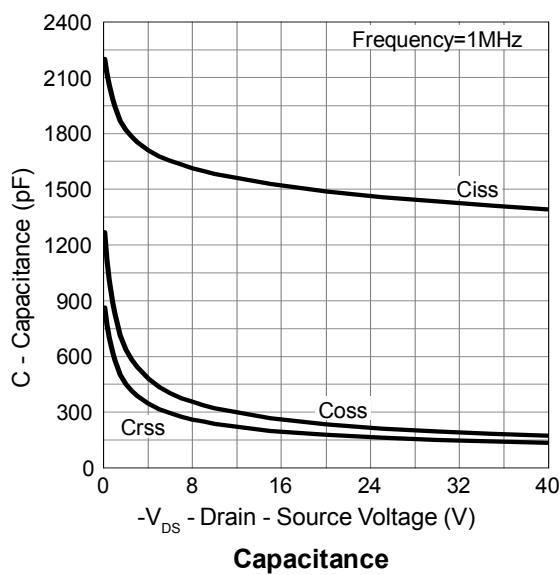
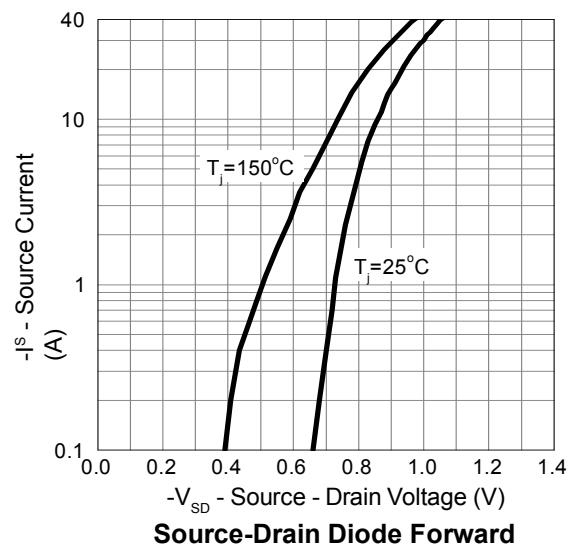
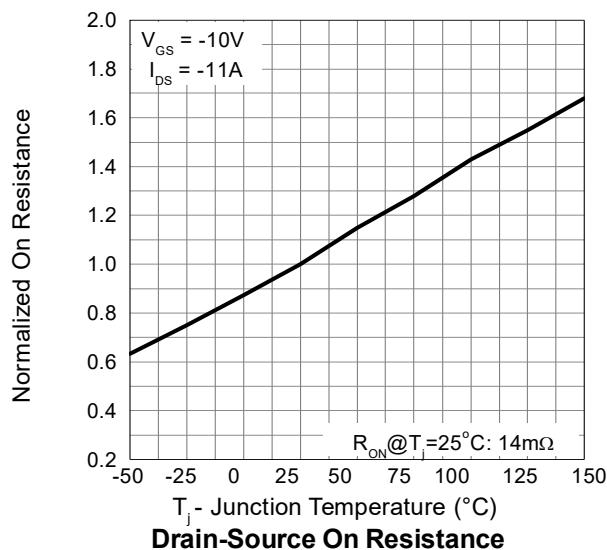
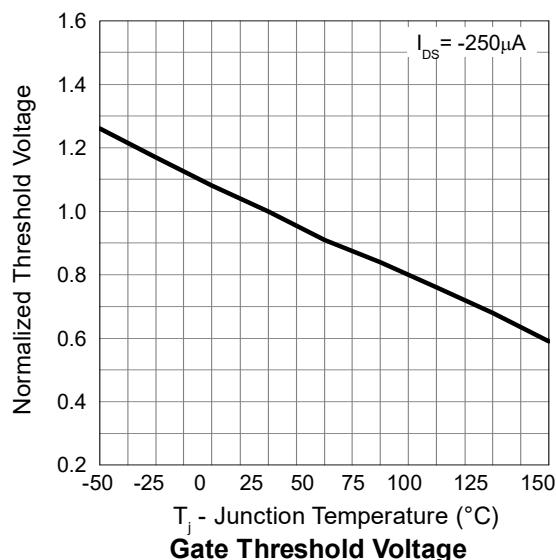
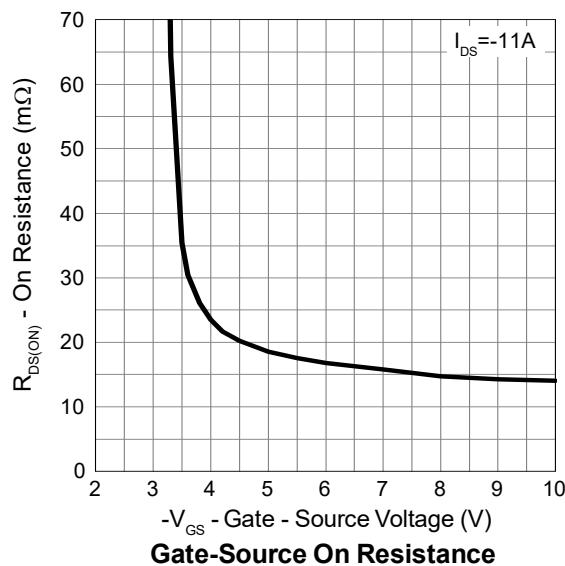
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|------------------------|--|-----|-------|-----|------|
| Continuous Source Current ^{1,5} | I_s | $\text{V}_G=\text{V}_D=0\text{V}$, Force Current | --- | --- | -3 | A |
| Diode Forward Voltage ² | V_{SD} | $\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=-1\text{A}$, $T_J=25^\circ\text{C}$ | --- | -0.75 | -1 | V |
| Reverse Recovery Time | t_{rr} | $\text{I}_F=-1\text{A}$, $d\text{i}/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$ | --- | 24 | --- | nS |
| | Q_{rr} | | --- | 18 | --- | nC |

Note:

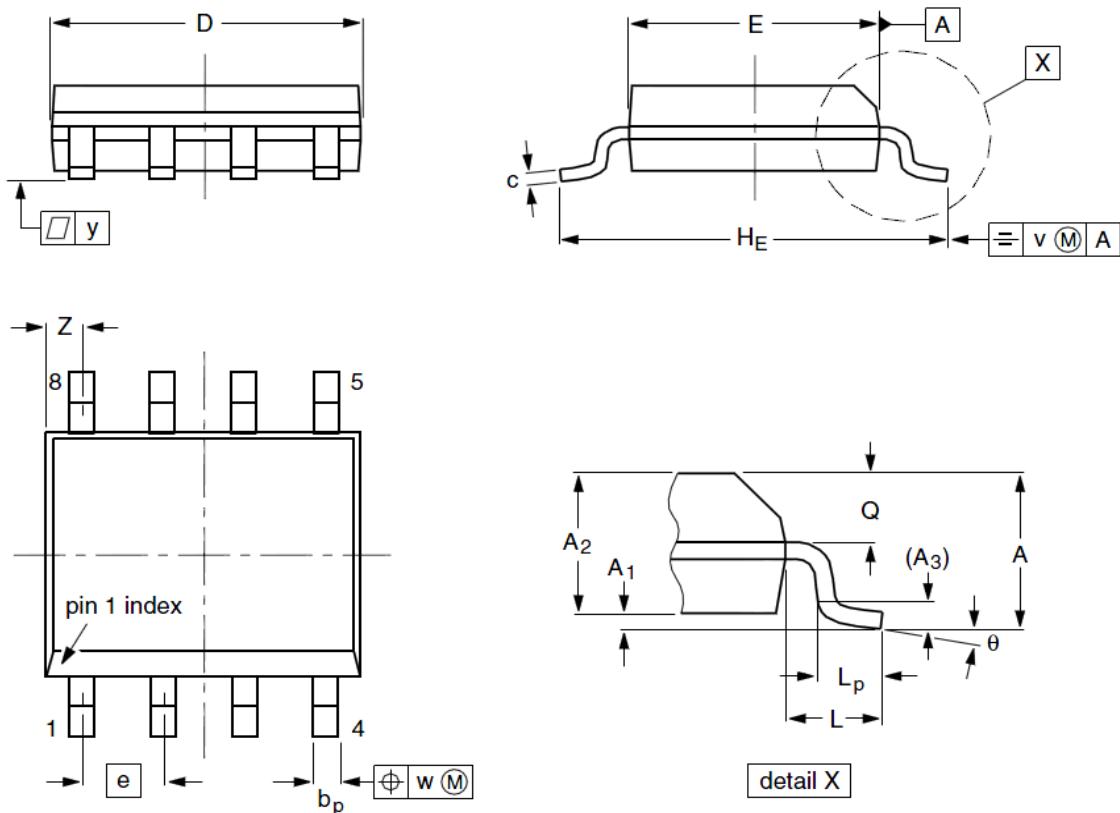
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=-25\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics





SOP-8 Package Outline Dimensions



| Symbol | Dimensions (unit:mm) | | | Symbol | Dimensions (unit:mm) | | |
|----------------------|----------------------|------|------|----------------------|----------------------|------|------|
| | Min | Typ | Max | | Min | Typ | Max |
| A | 1.35 | 1.55 | 1.75 | A₁ | 0.10 | 0.18 | 0.25 |
| A₂ | 1.25 | 1.45 | 1.65 | A₃ | -- | 0.25 | -- |
| b_p | 0.36 | 0.42 | 0.51 | c | 0.19 | 0.22 | 0.25 |
| D | 4.70 | 4.92 | 5.10 | E | 3.80 | 3.90 | 4.00 |
| e | -- | 1.27 | -- | H_E | 5.80 | 6.00 | 6.20 |
| L | -- | 1.05 | -- | L_P | 0.40 | 0.68 | 1.00 |
| Q | 0.60 | 0.65 | 0.73 | v | -- | 0.25 | -- |
| w | -- | 0.25 | -- | y | -- | 0.10 | -- |
| Z | 0.30 | 0.50 | 0.70 | θ | 0° | | 8° |